&TDK Multilayer Ceramic Chip Capacitors

C2012X5R1V226M125AC



TDK item description C2012X5R1V226MT****

Applications	Commercial Grade
Feature	General General (Up to 50V)
Series	C2012 [EIA 0805]
Status	Production

	Size
Length(L)	2.00mm ±0.20mm
Width(W)	1.25mm ±0.20mm
Thickness(T)	1.25mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.50mm Min.
Recommended Land Pattern (PA)	1.00mm to 1.30mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.00mm to 1.20mm(Flow Soldering)
	0.70mm to 0.90mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.80mm to 1.10mm(Flow Soldering)
	0.90mm to 1.20mm(Reflow Soldering)

Electrical Characteristics		
Capacitance	22µF ±20%	
Rated Voltage	35VDC	
Temperature Characteristic	X5R(±15%)	
Dissipation Factor (Max.)	10%	
Insulation Resistance (Min.)	22ΜΩ	

Other		
Coldering Mathed	Wave (Flow)	
Soldering Method	Reflow	
AEC-Q200	No	
Packing	Blister (Plastic)Taping [180mm Reel]	
Package Quantity	2000pcs	

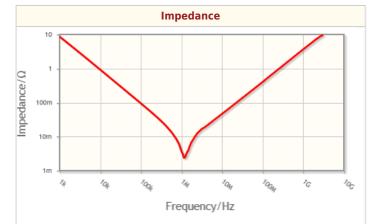
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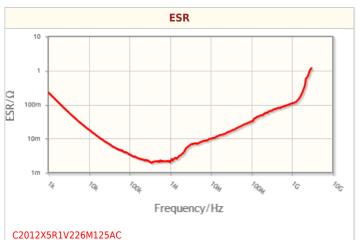
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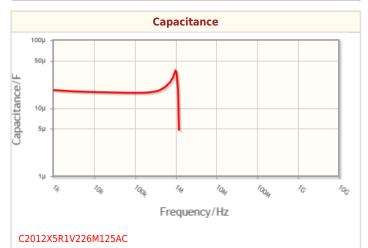


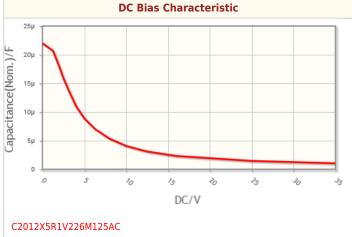


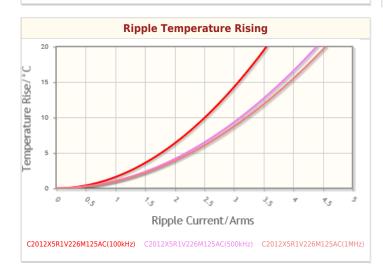
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)



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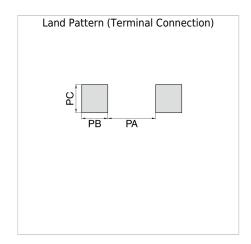
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Associated Images



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